



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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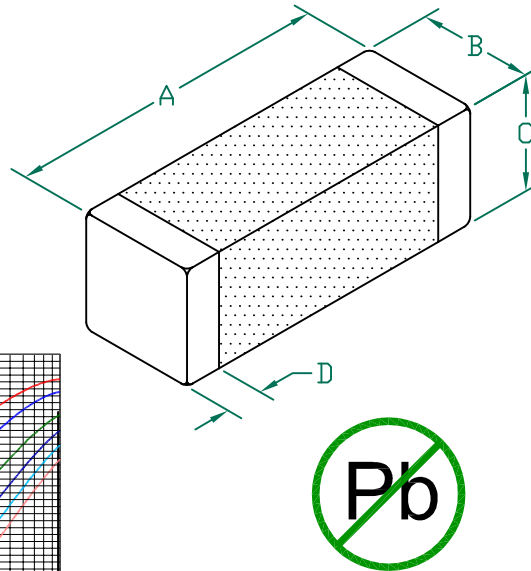


HI1806T600R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

A	4.50 [.177]	+ 0.25 [.010]
B	1.60 [.063]	+ 0.25 [.010]
C	1.60 [.063]	+ 0.25 [.010]
D	0.51 [.020]	+ 0.25 [.010]



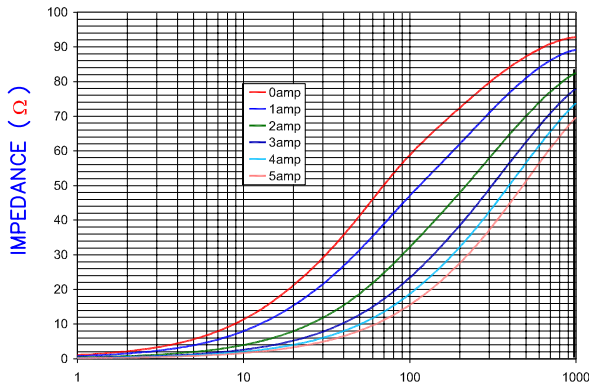
ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	60		
Minimum	45		
Maximum	75	0.010	6000 mA

NOTES: UNLESS OTHERWISE SPECIFIED

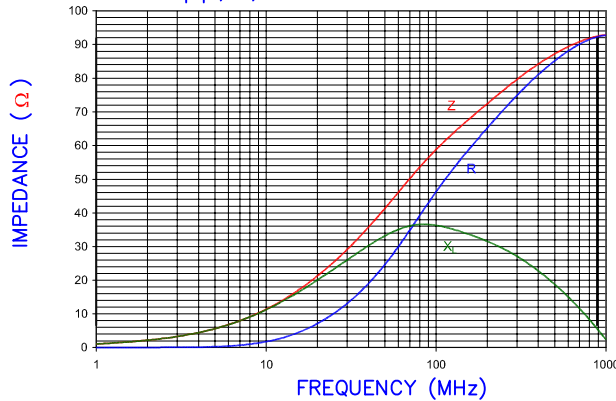
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 2,000 PCS/REEL. EMBOSSED PLASTIC TAPE.
2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
3. TERMINATION FINISH IS 100% TIN.
4. OPERATEING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)

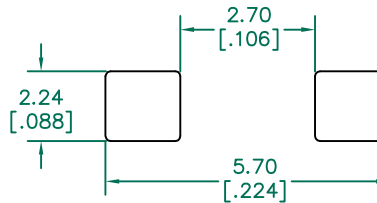
|Z|, R, AND X vs. FREQUENCY



FREQUENCY (MHz)

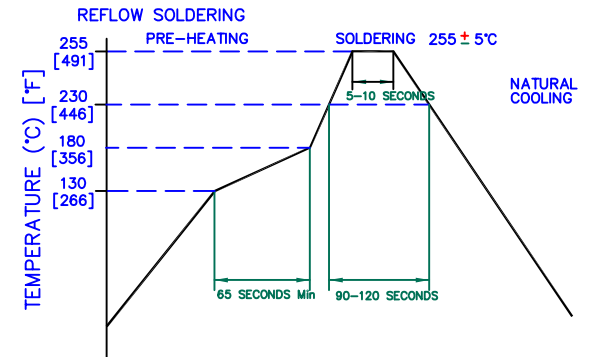
Z R X_L

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [.030] to this dimension.)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.		Laird		
H	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	PROJECT/PART NUMBER: HI1806T600R-10		REV	PART TYPE:	DRAWN BY:
G	CHANGE SOLDERING TEMPERATURE FROM 250	07/08/10	JUN			H	CO-FIRE	BAC
F	CHANGE REEL QTY FROM 3K TO 2K	11/06/08	JRK			DATE:	SCALE:	SHEET:
E	UPDATE COMPANY LOGO	06/19/08	JRK			01/12/01	NTS	2 of 2
D	UPDATE COMPANY LOGO ADD ROHS SYMBOL	01/18/08	JRK			GAD #	TOOL #	
C	ADD DC BIAS CURVE, CORRECT LANDPATTERN	03/07/03	JRK			DATE:		
B	REMOVE NOTE 3	09/14/01	JRK			INT		
A	ORIGINAL DRAFT	01/12/01	BAC					
REV	DESCRIPTION	DATE	INT					